

# Undervoltage Sensing Circuit

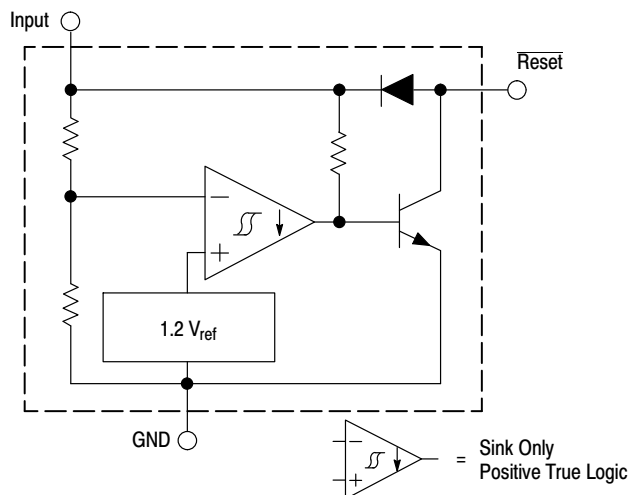
## MC34064, MC33064, NCV33064

The MC34064 is an undervoltage sensing circuit specifically designed for use as a reset controller in microprocessor-based systems. It offers the designer an economical solution for low voltage detection with a single external resistor. The MC34064 features a trimmed-in-package bandgap reference, and a comparator with precise thresholds and built-in hysteresis to prevent erratic reset operation. The open collector reset output is capable of sinking in excess of 10 mA, and operation is guaranteed down to 1.0 V input with low standby current. The MC devices are packaged in 3-pin TO-92, micro size TSOP-5, 8-pin SOIC-8 and Micro8 surface mount packages. The NCV device is packaged in SOIC-8 and TO-92.

Applications include direct monitoring of the 5.0 V MPU/logic power supply used in appliance, automotive, consumer and industrial equipment.

### Features

- Trimmed-In-Package Temperature Compensated Reference
- Comparator Threshold of 4.6 V at 25°C
- Precise Comparator Thresholds Guaranteed Over Temperature
- Comparator Hysteresis Prevents Erratic Reset
- Reset Output Capable of Sinking in Excess of 10 mA
- Internal Clamp Diode for Discharging Delay Capacitor
- Guaranteed Reset Operation with 1.0 V Input
- Low Standby Current
- Economical TO-92, TSOP-5, SOIC-8 and Micro8 Surface Mount Packages
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes
- These Devices are Pb-Free and are RoHS Compliant



This device contains 21 active transistors.

**Figure 1. Representative Block Diagram**



SOIC-8  
D SUFFIX  
CASE 751

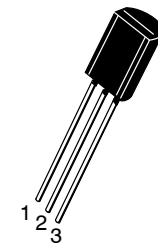


Micro8  
DM SUFFIX  
CASE 846A

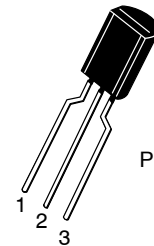


TSOP-5  
SN SUFFIX  
CASE 483

Pin 1. Ground  
2. Input  
3. Reset  
4. NC  
5. NC



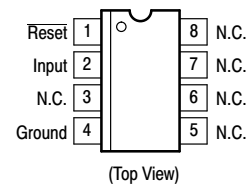
STRAIGHT LEAD



TO-92  
CASE 29-10

Pin: 1. Reset  
2. Input  
3. Ground

### PIN CONNECTIONS



### ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

### DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 7 of this data sheet.

# MC34064, MC33064, NCV33064

## MAXIMUM RATINGS

| Rating                                                   | Symbol          | Value              | Unit               |
|----------------------------------------------------------|-----------------|--------------------|--------------------|
| Power Input Supply Voltage                               | $V_{in}$        | -1.0 to 10         | V                  |
| Reset Output Voltage                                     | $V_O$           | 10                 | V                  |
| Reset Output Sink Current (Note 2)                       | $I_{Sink}$      | Internally Limited | mA                 |
| Clamp Diode Forward Current, Reset to Input Pin (Note 2) | $I_F$           | 100                | mA                 |
| Power Dissipation and Thermal Characteristics            |                 |                    |                    |
| P Suffix, Plastic Package                                |                 |                    |                    |
| Maximum Power Dissipation @ $T_A = 25^\circ\text{C}$     | $P_D$           | 625                | mW                 |
| Thermal Resistance, Junction-to-Air                      | $R_{\theta JA}$ | 200                | $^\circ\text{C/W}$ |
| D Suffix, Plastic Package                                |                 |                    |                    |
| Maximum Power Dissipation @ $T_A = 25^\circ\text{C}$     | $P_D$           | 625                | mW                 |
| Thermal Resistance, Junction-to-Air                      | $R_{\theta JA}$ | 200                | $^\circ\text{C/W}$ |
| DM Suffix, Plastic Package                               |                 |                    |                    |
| Maximum Power Dissipation @ $T_A = 25^\circ\text{C}$     | $P_D$           | 520                | mW                 |
| Thermal Resistance, Junction-to-Air                      | $R_{\theta JA}$ | 240                | $^\circ\text{C/W}$ |
| Operating Junction Temperature                           | $T_J$           | +150               | $^\circ\text{C}$   |
| Operating Ambient Temperature                            | $T_A$           |                    | $^\circ\text{C}$   |
| MC34064                                                  |                 | 0 to +70           |                    |
| MC33064                                                  |                 | -40 to +85         |                    |
| NCV33064                                                 |                 | -40 to +125        |                    |
| Storage Temperature Range                                | $T_{stg}$       | -65 to +150        | $^\circ\text{C}$   |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. ESD data available upon request.

**ELECTRICAL CHARACTERISTICS** (For typical values  $T_A = 25^\circ\text{C}$ , for min/max values  $T_A$  is the operating ambient temperature range that applies [Notes 3 and 4] unless otherwise noted.)

| Characteristics | Symbol | Min | Typ | Max | Unit |
|-----------------|--------|-----|-----|-----|------|
|-----------------|--------|-----|-----|-----|------|

### COMPARATOR

|                                          |          |      |      |      |   |
|------------------------------------------|----------|------|------|------|---|
| Threshold Voltage                        |          |      |      |      | V |
| High State Output ( $V_{in}$ Increasing) | $V_{IH}$ | 4.5  | 4.61 | 4.7  |   |
| Low State Output ( $V_{in}$ Decreasing)  | $V_{IL}$ | 4.5  | 4.59 | 4.7  |   |
| Hysteresis                               | $V_H$    | 0.01 | 0.02 | 0.05 |   |

### RESET OUTPUT

|                                                                          |            |     |      |     |               |
|--------------------------------------------------------------------------|------------|-----|------|-----|---------------|
| Output Sink Saturation                                                   | $V_{OL}$   |     |      |     | V             |
| ( $V_{in} = 4.0\text{ V}$ , $I_{Sink} = 8.0\text{ mA}$ )                 |            | –   | 0.46 | 1.0 |               |
| ( $V_{in} = 4.0\text{ V}$ , $I_{Sink} = 2.0\text{ mA}$ )                 |            | –   | 0.15 | 0.4 |               |
| ( $V_{in} = 1.0\text{ V}$ , $I_{Sink} = 0.1\text{ mA}$ )                 |            | –   | –    | 0.1 |               |
| Output Sink Current ( $V_{in}$ , $\text{Reset} = 4.0\text{ V}$ )         | $I_{Sink}$ | 10  | 27   | 60  | mA            |
| Output Off-State Leakage ( $V_{in}$ , $\text{Reset} = 5.0\text{ V}$ )    | $I_{OH}$   | –   | 0.02 | 0.5 | $\mu\text{A}$ |
| Clamp Diode Forward Voltage, Reset to Input Pin ( $I_F = 10\text{ mA}$ ) | $V_F$      | 0.6 | 0.9  | 1.2 | V             |

### TOTAL DEVICE

|                                                     |          |            |     |     |               |
|-----------------------------------------------------|----------|------------|-----|-----|---------------|
| Operating Input Voltage Range                       | $V_{in}$ | 1.0 to 6.5 | –   | –   | V             |
| Quiescent Input Current ( $V_{in} = 5.0\text{ V}$ ) | $I_{in}$ | –          | 390 | 500 | $\mu\text{A}$ |

- Maximum package power dissipation limits must be observed.
- Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.
- $T_{low} = 0^\circ\text{C}$  for MC34064       $T_{high} = +70^\circ\text{C}$  for MC34064  
      $-40^\circ\text{C}$  for MC33064       $+85^\circ\text{C}$  for MC33064  
      $-40^\circ\text{C}$  for NCV33064       $+125^\circ\text{C}$  for NCV33064
- NCV prefix is for automotive and other applications requiring site and change control.

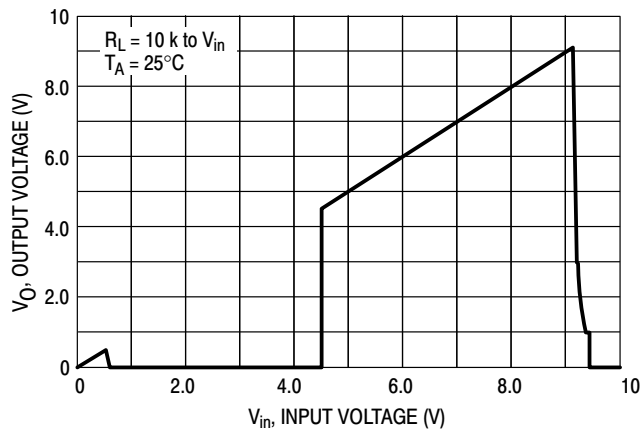


Figure 2. Reset Output Voltage versus Input Voltage

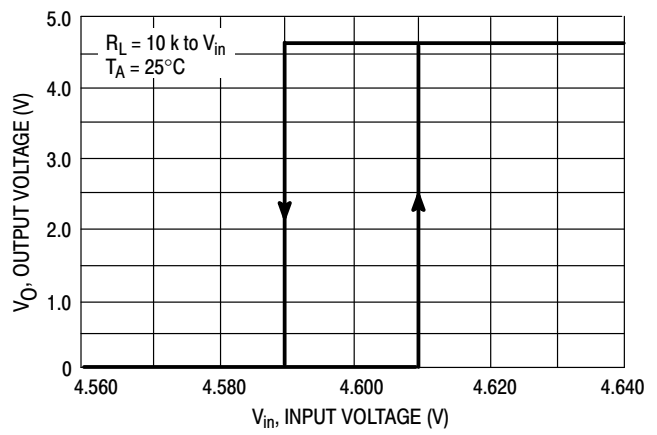


Figure 3. Reset Output Voltage versus Input Voltage

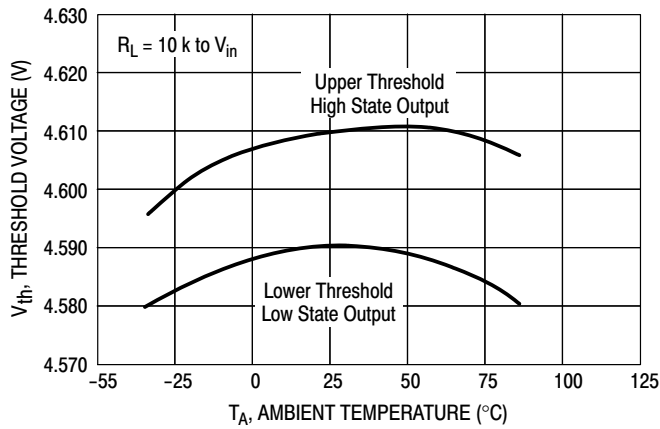


Figure 4. Comparator Threshold Voltage versus Temperature

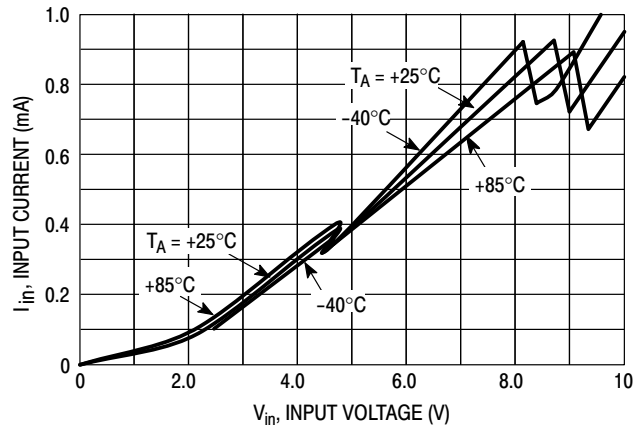


Figure 5. Input Current versus Input Voltage

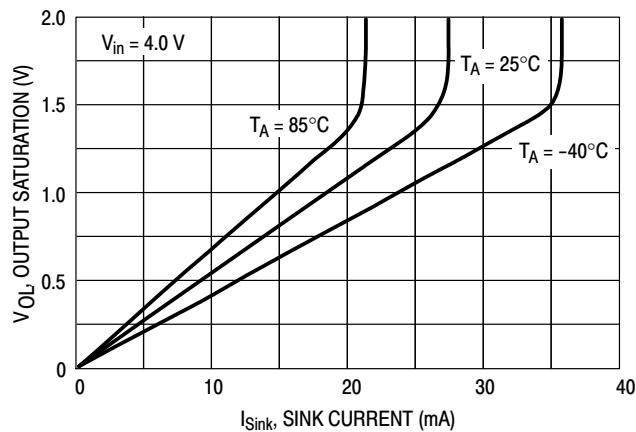


Figure 6. Reset Output Saturation versus Sink Current

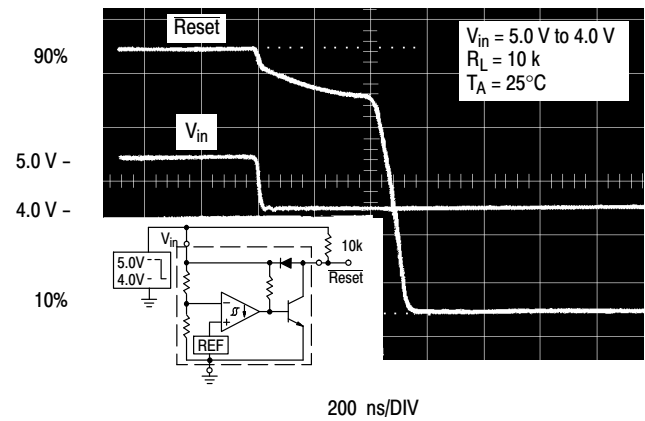


Figure 7. Reset Delay Time

# MC34064, MC33064, NCV33064

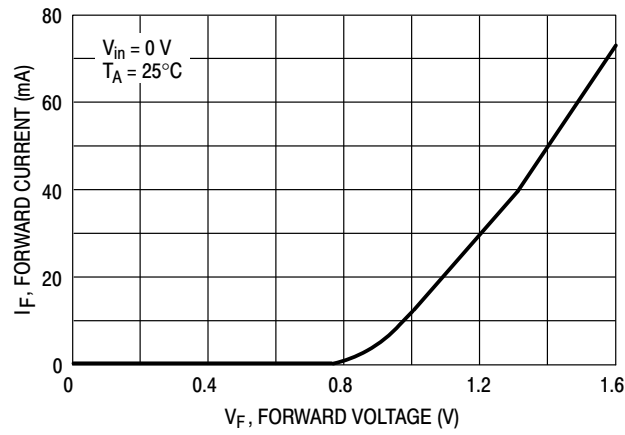


Figure 8. Clamp Diode Forward Current versus Voltage

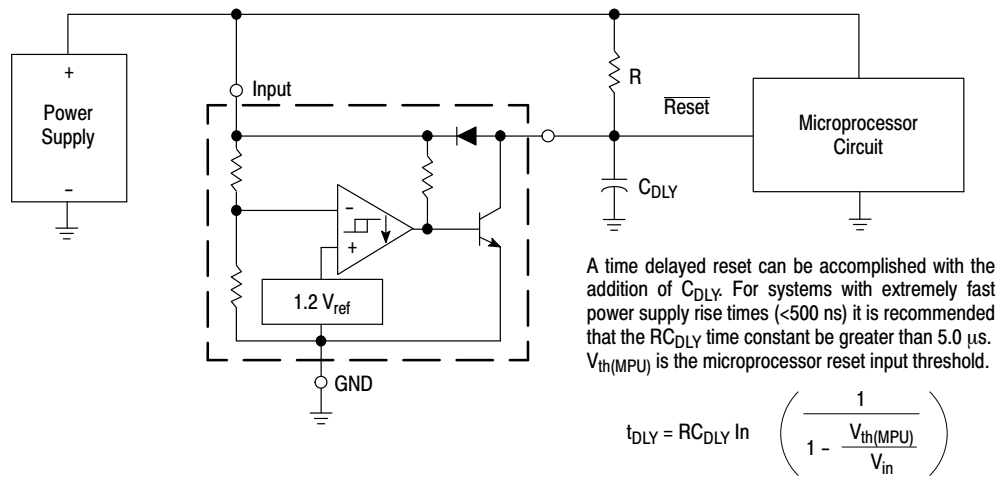
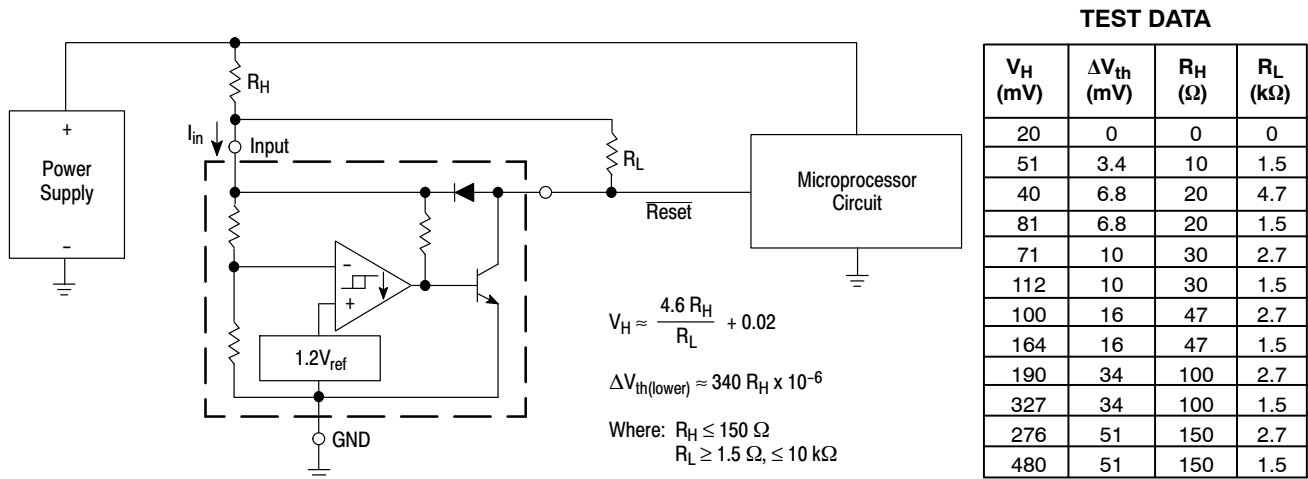


Figure 9. Low Voltage Microprocessor Reset



Comparator hysteresis can be increased with the addition of resistor  $R_H$ . The hysteresis equation has been simplified and does not account for the change of input current  $I_{in}$  as  $V_{CC}$  crosses the comparator threshold (Figure 4). An increase of the lower threshold  $\Delta V_{th(lower)}$  will be observed due to  $I_{in}$  which is typically  $340\text{ }\mu\text{A}$  at  $4.59\text{ V}$ . The equations are accurate to  $\pm 10\%$  with  $R_H$  less than  $150\text{ }\Omega$  and  $R_L$  between  $1.5\text{ k}\Omega$  and  $10\text{ k}\Omega$ .

Figure 10. Low Voltage Microprocessor Reset with Additional Hysteresis

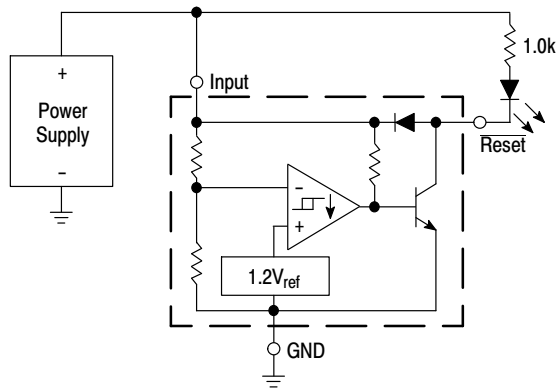


Figure 11. Voltage Monitor

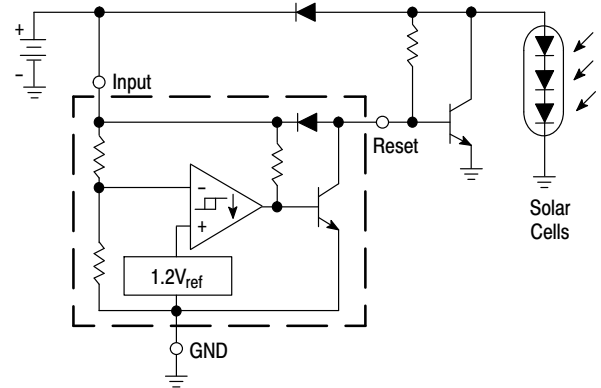
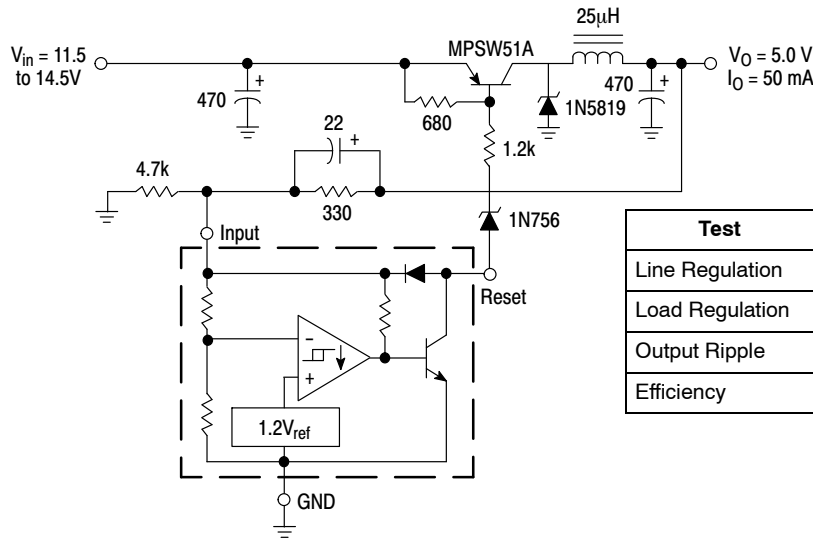
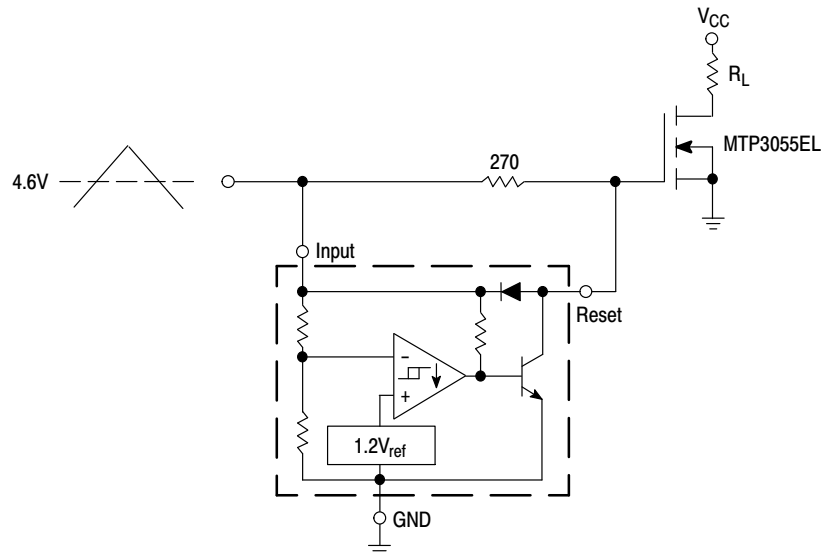


Figure 12. Solar Powered Battery Charger



| Test            | Conditions                                                           | Results |
|-----------------|----------------------------------------------------------------------|---------|
| Line Regulation | $V_{in} = 11.5 \text{ V to } 14.5 \text{ V}$ , $I_O = 50 \text{ mA}$ | 35 mV   |
| Load Regulation | $V_{in} = 12.6 \text{ V}$ , $I_O = 0 \text{ mA to } 50 \text{ mA}$   | 12 mV   |
| Output Ripple   | $V_{in} = 12.6 \text{ V}$ , $I_O = 50 \text{ mA}$                    | 60 mVpp |
| Efficiency      | $V_{in} = 12.6 \text{ V}$ , $I_O = 50 \text{ mA}$                    | 77%     |

Figure 13. Low Power Switching Regulator



Overheating of the logic level power MOSFET due to insufficient gate voltage can be prevented with the above circuit. When the input signal is below the 4.6 V threshold of the MC34064, its output grounds the gate of the L<sup>2</sup> MOSFET.

Figure 14. MOSFET Low Voltage Gate Drive Protection

# MC34064, MC33064, NCV33064

## ORDERING INFORMATION

| Device           | Operating Temperature Range                           | Package             | Shipping <sup>†</sup>    |
|------------------|-------------------------------------------------------|---------------------|--------------------------|
| MC34064D-5G      | $T_A = 0^{\circ}\text{C}$ to $+70^{\circ}\text{C}$    | SOIC-8<br>(Pb-Free) | 98 Units / Rail          |
| MC34064D-5R2G    |                                                       | SOIC-8<br>(Pb-Free) | 2500 Units / Tape & Reel |
| MC34064DM-5R2G   |                                                       | Micro8<br>(Pb-Free) | 4000 Units / Tape & Reel |
| MC34064P-5G      |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Bag         |
| MC34064P-5RAG    |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Tape & Reel |
| MC34064P-5RPG    |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Ammo Pack   |
| MC34064P-5RMG    |                                                       | TO-92<br>(Pb-Free)  |                          |
| MC34064SN-5T1G   |                                                       | TSOP-5<br>(Pb-Free) | 3000 Units / Tape & Reel |
| MC33064D-5G      | $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$  | SOIC-8<br>(Pb-Free) | 98 Units / Rail          |
| MC33064D-5R2G    |                                                       | SOIC-8<br>(Pb-Free) | 2500 Units / Tape & Reel |
| MC33064DM-5R2G   |                                                       | Micro8<br>(Pb-Free) | 4000 Units / Tape & Reel |
| MC33064P-5G      |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Bag         |
| MC33064P-5RAG    |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Tape & Reel |
| MC33064P-5RPG    |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Ammo Pack   |
| MC33064SN-5T1G   |                                                       | TSOP-5<br>(Pb-Free) | 3000 Units / Tape & Reel |
| NCV33064D-5R2G*  | $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ | SOIC-8<br>(Pb-Free) | 2500 Units / Tape & Reel |
| NCV33064P-5RAG*  |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Tape & Reel |
| NCV33064P-5RPG*  |                                                       | TO-92<br>(Pb-Free)  | 2000 Units / Ammo Pack   |
| NCV33064DM-5R2G* |                                                       | Micro8<br>(Pb-Free) | 4000 Units / Tape & Reel |

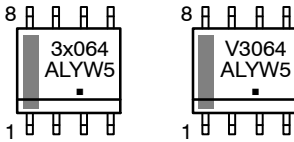
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NCV33064:  $T_{\text{low}} = -40^{\circ}\text{C}$ ,  $T_{\text{high}} = +125^{\circ}\text{C}$ . Guaranteed by design. NCV prefix is for automotive and other applications requiring site and change control.

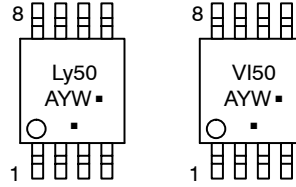
# MC34064, MC33064, NCV33064

## MARKING DIAGRAMS

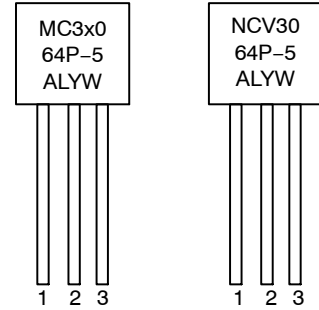
**SOIC-8**  
**D SUFFIX**  
**CASE 751**



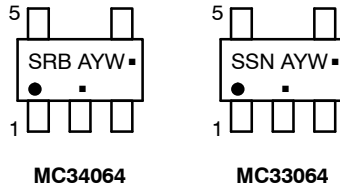
**Micro8**  
**DM SUFFIX**  
**CASE 846A**



**TO-92**  
**P SUFFIX**  
**CASE 029**



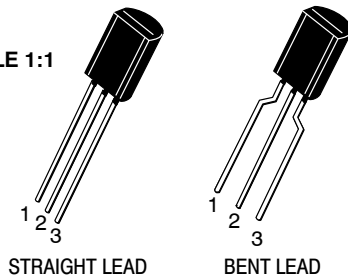
**TSOP-5**  
**SN SUFFIX**  
**CASE 483**



- x = 3 or 4
- y = C or I
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

SCALE 1:1



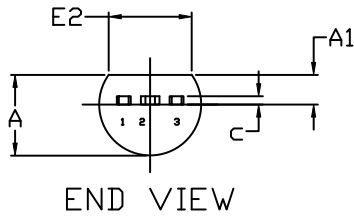
STRAIGHT LEAD

BENT LEAD

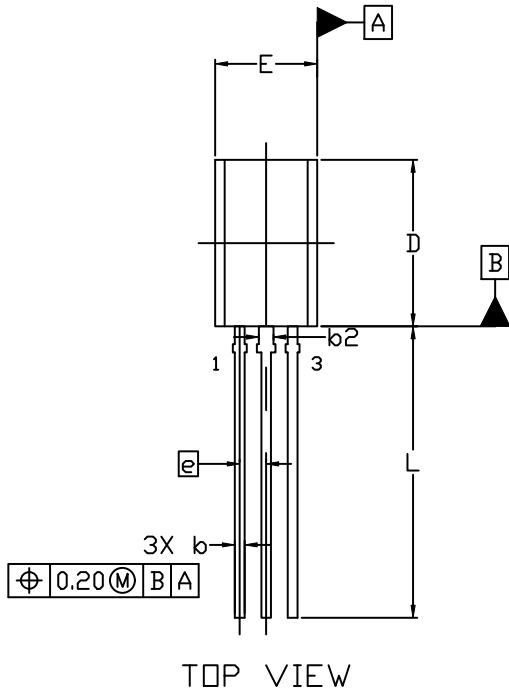
**TO-92 (TO-226) 1 WATT**  
CASE 29-10  
ISSUE D

DATE 05 MAR 2021

## STRAIGHT LEAD



END VIEW



TOP VIEW

### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

| DIM | MILLIMETERS |       |       |
|-----|-------------|-------|-------|
|     | MIN.        | NOM.  | MAX.  |
| A   | 3.75        | 3.90  | 4.05  |
| A1  | 1.28        | 1.43  | 1.58  |
| b   | 0.38        | 0.465 | 0.55  |
| b2  | 0.62        | 0.70  | 0.78  |
| c   | 0.35        | 0.40  | 0.45  |
| D   | 7.85        | 8.00  | 8.15  |
| E   | 4.75        | 4.90  | 5.05  |
| E2  | 3.90        | ---   | ---   |
| e   | 1.27 BSC    |       |       |
| L   | 13.80       | 14.00 | 14.20 |

## STYLES AND MARKING ON PAGE 3

|                         |                              |                                                                                                                                                                                  |
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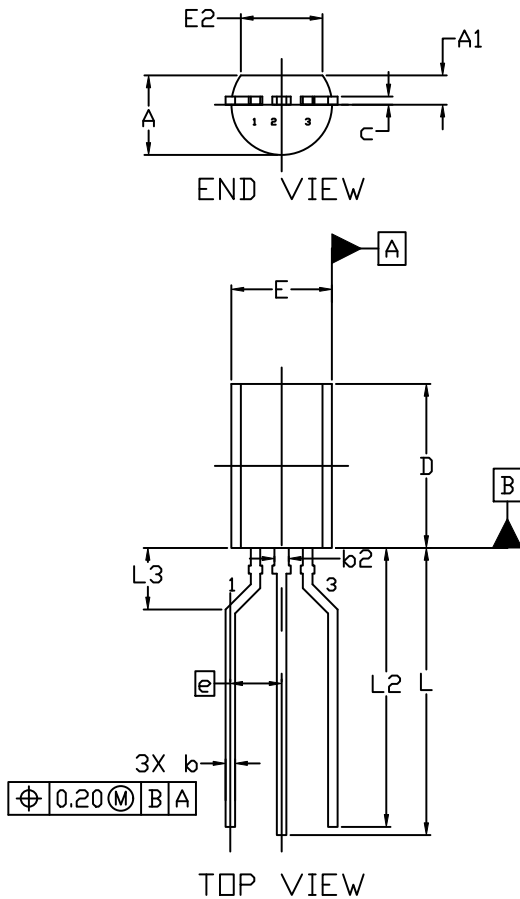
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**TO-92 (TO-226) 1 WATT**  
CASE 29-10  
ISSUE D

DATE 05 MAR 2021

**FORMED LEAD**



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

| DIM | MILLIMETERS |       |       |
|-----|-------------|-------|-------|
|     | MIN.        | NOM.  | MAX.  |
| A   | 3.75        | 3.90  | 4.05  |
| A1  | 1.28        | 1.43  | 1.58  |
| b   | 0.38        | 0.465 | 0.55  |
| b2  | 0.62        | 0.70  | 0.78  |
| c   | 0.35        | 0.40  | 0.45  |
| D   | 7.85        | 8.00  | 8.15  |
| E   | 4.75        | 4.90  | 5.05  |
| E2  | 3.90        | ---   | ---   |
| e   | 2.50 BSC    |       |       |
| L   | 13.80       | 14.00 | 14.20 |
| L2  | 13.20       | 13.60 | 14.00 |
| L3  | 3.00 REF    |       |       |

**STYLES AND MARKING ON PAGE 3**

|                         |                              |                                                                                                                                                                                  |
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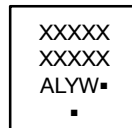
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**TO-92 (TO-226) 1 WATT**  
**CASE 29-10**  
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|                                                                 |                                                                      |                                                              |                                                                 |                                                             |
|-----------------------------------------------------------------|----------------------------------------------------------------------|--------------------------------------------------------------|-----------------------------------------------------------------|-------------------------------------------------------------|
| STYLE 1:<br>PIN 1. EMITTER<br>2. BASE<br>3. COLLECTOR           | STYLE 2:<br>PIN 1. BASE<br>2. EMITTER<br>3. COLLECTOR                | STYLE 3:<br>PIN 1. ANODE<br>2. ANODE<br>3. CATHODE           | STYLE 4:<br>PIN 1. CATHODE<br>2. CATHODE<br>3. ANODE            | STYLE 5:<br>PIN 1. DRAIN<br>2. SOURCE<br>3. GATE            |
| STYLE 6:<br>PIN 1. GATE<br>2. SOURCE & SUBSTRATE<br>3. DRAIN    | STYLE 7:<br>PIN 1. SOURCE<br>2. DRAIN<br>3. GATE                     | STYLE 8:<br>PIN 1. DRAIN<br>2. GATE<br>3. SOURCE & SUBSTRATE | STYLE 9:<br>PIN 1. BASE 1<br>2. EMITTER<br>3. BASE 2            | STYLE 10:<br>PIN 1. CATHODE<br>2. GATE<br>3. ANODE          |
| STYLE 11:<br>PIN 1. ANODE<br>2. CATHODE & ANODE<br>3. CATHODE   | STYLE 12:<br>PIN 1. MAIN TERMINAL 1<br>2. GATE<br>3. MAIN TERMINAL 2 | STYLE 13:<br>PIN 1. ANODE 1<br>2. GATE<br>3. CATHODE 2       | STYLE 14:<br>PIN 1. EMITTER<br>2. COLLECTOR<br>3. BASE          | STYLE 15:<br>PIN 1. ANODE 1<br>2. CATHODE<br>3. ANODE 2     |
| STYLE 16:<br>PIN 1. ANODE<br>2. GATE<br>3. CATHODE              | STYLE 17:<br>PIN 1. COLLECTOR<br>2. BASE<br>3. EMITTER               | STYLE 18:<br>PIN 1. ANODE<br>2. CATHODE<br>3. NOT CONNECTED  | STYLE 19:<br>PIN 1. GATE<br>2. ANODE<br>3. CATHODE              | STYLE 20:<br>PIN 1. NOT CONNECTED<br>2. CATHODE<br>3. ANODE |
| STYLE 21:<br>PIN 1. COLLECTOR<br>2. EMITTER<br>3. BASE          | STYLE 22:<br>PIN 1. SOURCE<br>2. GATE<br>3. DRAIN                    | STYLE 23:<br>PIN 1. GATE<br>2. SOURCE<br>3. DRAIN            | STYLE 24:<br>PIN 1. EMITTER<br>2. COLLECTOR/ANODE<br>3. CATHODE | STYLE 25:<br>PIN 1. MT 1<br>2. GATE<br>3. MT 2              |
| STYLE 26:<br>PIN 1. V <sub>CC</sub><br>2. GROUND 2<br>3. OUTPUT | STYLE 27:<br>PIN 1. MT<br>2. SUBSTRATE<br>3. MT                      | STYLE 28:<br>PIN 1. CATHODE<br>2. ANODE<br>3. GATE           | STYLE 29:<br>PIN 1. NOT CONNECTED<br>2. ANODE<br>3. CATHODE     | STYLE 30:<br>PIN 1. DRAIN<br>2. GATE<br>3. SOURCE           |
| STYLE 31:<br>PIN 1. GATE<br>2. DRAIN<br>3. SOURCE               | STYLE 32:<br>PIN 1. BASE<br>2. COLLECTOR<br>3. EMITTER               | STYLE 33:<br>PIN 1. RETURN<br>2. INPUT<br>3. OUTPUT          | STYLE 34:<br>PIN 1. INPUT<br>2. GROUND<br>3. LOGIC              | STYLE 35:<br>PIN 1. GATE<br>2. COLLECTOR<br>3. EMITTER      |

**GENERIC  
MARKING DIAGRAM\***



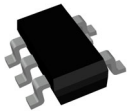
XXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
■ = Pb-Free Package

(Note: Microdot may be in either location)

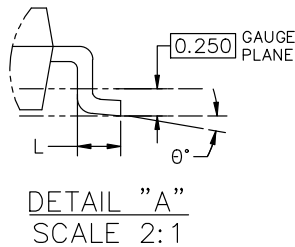
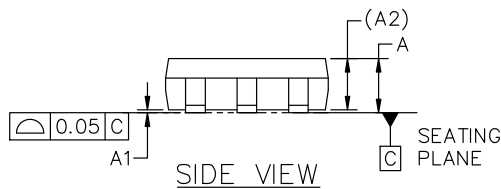
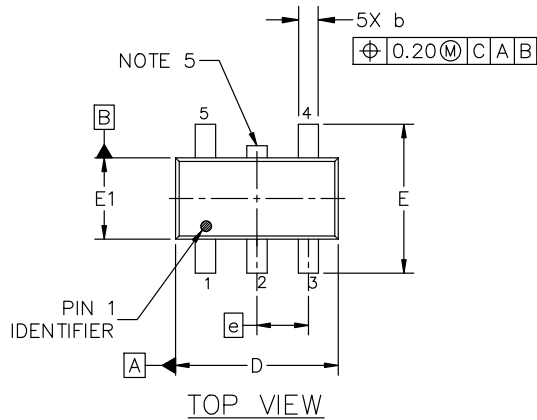
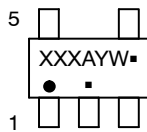
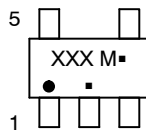
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

|                         |                              |                                                                                                                                                                                     |
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| <b>DESCRIPTION:</b>     | <b>TO-92 (TO-226) 1 WATT</b> | <b>PAGE 3 OF 3</b>                                                                                                                                                                  |

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**TSOP-5 3.00x1.50x0.95, 0.95P**  
**CASE 483**  
**ISSUE P**

DATE 01 APR 2024


**GENERIC**  
**MARKING DIAGRAM\***

**Analog**

**Discrete/Logic**

XXX = Specific Device Code    XXX = Specific Device Code  
A = Assembly Location    M = Date Code  
Y = Year    ■ = Pb-Free Package  
W = Work Week  
■ = Pb-Free Package

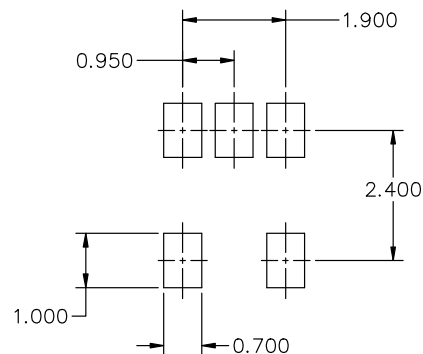
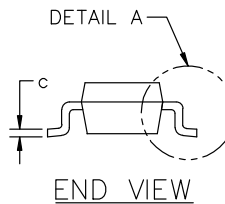
(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

## NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES).
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION D.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

| DIM | MILLIMETERS |       |       |
|-----|-------------|-------|-------|
|     | MIN.        | NOM.  | MAX.  |
| A   | 0.900       | 1.000 | 1.100 |
| A1  | 0.010       | 0.055 | 0.100 |
| A2  | 0.950 REF.  |       |       |
| b   | 0.250       | 0.375 | 0.500 |
| c   | 0.100       | 0.180 | 0.260 |
| D   | 2.850       | 3.000 | 3.150 |
| E   | 2.500       | 2.750 | 3.000 |
| E1  | 1.350       | 1.500 | 1.650 |
| e   | 0.950 BSC   |       |       |
| L   | 0.200       | 0.400 | 0.600 |
| θ   | 0°          | 5°    | 10°   |


**RECOMMENDED MOUNTING FOOTPRINT\***

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

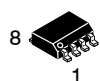
**DOCUMENT NUMBER:** 98ARB18753C

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**DESCRIPTION:** TSOP-5 3.00x1.50x0.95, 0.95P

**PAGE 1 OF 1**

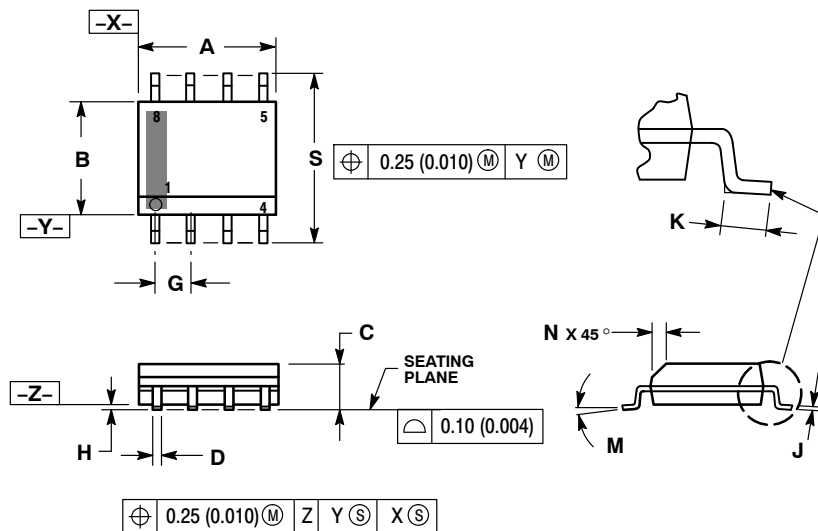
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SCALE 1:1

SOIC-8 NB  
CASE 751-07  
ISSUE AK

DATE 16 FEB 2011

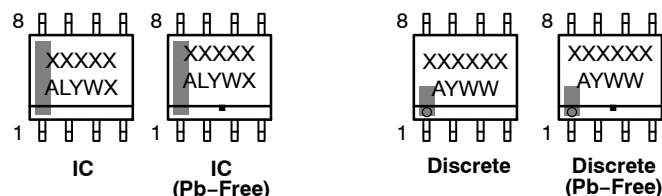
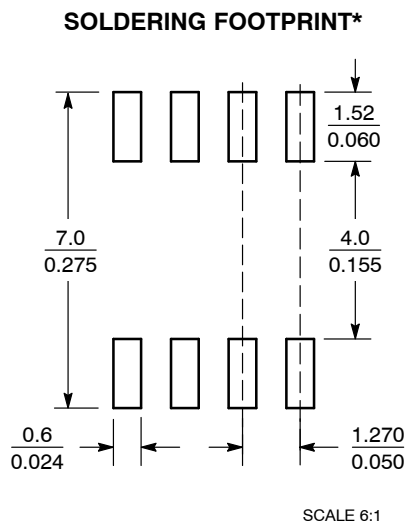


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

|     | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
| DIM | MIN         | MAX  | MIN       | MAX   |
| A   | 4.80        | 5.00 | 0.189     | 0.197 |
| B   | 3.80        | 4.00 | 0.150     | 0.157 |
| C   | 1.35        | 1.75 | 0.053     | 0.069 |
| D   | 0.33        | 0.51 | 0.013     | 0.020 |
| G   | 1.27 BSC    |      | 0.050 BSC |       |
| H   | 0.10        | 0.25 | 0.004     | 0.010 |
| J   | 0.19        | 0.25 | 0.007     | 0.010 |
| K   | 0.40        | 1.27 | 0.016     | 0.050 |
| M   | 0°          | 8°   | 0°        | 8°    |
| N   | 0.25        | 0.50 | 0.010     | 0.020 |
| S   | 5.80        | 6.20 | 0.228     | 0.244 |

GENERIC  
MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

XXXXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

|                  |             |                                                                                                                                                                                     |
|------------------|-------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| DESCRIPTION:     | SOIC-8 NB   | PAGE 1 OF 2                                                                                                                                                                         |

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**SOIC-8 NB**  
**CASE 751-07**  
**ISSUE AK**

DATE 16 FEB 2011

|                                                                                                                                                                                                   |                                                                                                                                                                                          |                                                                                                                                                                                    |                                                                                                                                                                                                        |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>STYLE 1:</b><br>PIN 1. EMITTER<br>2. COLLECTOR<br>3. COLLECTOR<br>4. EMITTER<br>5. EMITTER<br>6. BASE<br>7. BASE<br>8. EMITTER                                                                 | <b>STYLE 2:</b><br>PIN 1. COLLECTOR, DIE, #1<br>2. COLLECTOR, #1<br>3. COLLECTOR, #2<br>4. COLLECTOR, #2<br>5. BASE, #2<br>6. EMITTER, #2<br>7. BASE, #1<br>8. EMITTER, #1               | <b>STYLE 3:</b><br>PIN 1. DRAIN, DIE #1<br>2. DRAIN, #1<br>3. DRAIN, #2<br>4. DRAIN, #2<br>5. GATE, #2<br>6. SOURCE, #2<br>7. GATE, #1<br>8. SOURCE, #1                            | <b>STYLE 4:</b><br>PIN 1. ANODE<br>2. ANODE<br>3. ANODE<br>4. ANODE<br>5. ANODE<br>6. ANODE<br>7. ANODE<br>8. COMMON CATHODE                                                                           |
| <b>STYLE 5:</b><br>PIN 1. DRAIN<br>2. DRAIN<br>3. DRAIN<br>4. DRAIN<br>5. GATE<br>6. GATE<br>7. SOURCE<br>8. SOURCE                                                                               | <b>STYLE 6:</b><br>PIN 1. SOURCE<br>2. DRAIN<br>3. DRAIN<br>4. SOURCE<br>5. SOURCE<br>6. GATE<br>7. GATE<br>8. SOURCE                                                                    | <b>STYLE 7:</b><br>PIN 1. INPUT<br>2. EXTERNAL BYPASS<br>3. THIRD STAGE SOURCE<br>4. GROUND<br>5. DRAIN<br>6. GATE 3<br>7. SECOND STAGE Vd<br>8. FIRST STAGE Vd                    | <b>STYLE 8:</b><br>PIN 1. COLLECTOR, DIE #1<br>2. BASE, #1<br>3. BASE, #2<br>4. COLLECTOR, #2<br>5. COLLECTOR, #2<br>6. EMITTER, #2<br>7. EMITTER, #1<br>8. COLLECTOR, #1                              |
| <b>STYLE 9:</b><br>PIN 1. EMITTER, COMMON<br>2. COLLECTOR, DIE #1<br>3. COLLECTOR, DIE #2<br>4. EMITTER, COMMON<br>5. EMITTER, COMMON<br>6. BASE, DIE #2<br>7. BASE, DIE #1<br>8. EMITTER, COMMON | <b>STYLE 10:</b><br>PIN 1. GROUND<br>2. BIAS 1<br>3. OUTPUT<br>4. GROUND<br>5. GROUND<br>6. BIAS 2<br>7. INPUT<br>8. GROUND                                                              | <b>STYLE 11:</b><br>PIN 1. SOURCE 1<br>2. GATE 1<br>3. SOURCE 2<br>4. GATE 2<br>5. DRAIN 2<br>6. DRAIN 2<br>7. DRAIN 1<br>8. DRAIN 1                                               | <b>STYLE 12:</b><br>PIN 1. SOURCE<br>2. SOURCE<br>3. SOURCE<br>4. GATE<br>5. DRAIN<br>6. DRAIN<br>7. DRAIN<br>8. DRAIN                                                                                 |
| <b>STYLE 13:</b><br>PIN 1. N.C.<br>2. SOURCE<br>3. SOURCE<br>4. GATE<br>5. DRAIN<br>6. DRAIN<br>7. DRAIN<br>8. DRAIN                                                                              | <b>STYLE 14:</b><br>PIN 1. N-SOURCE<br>2. N-GATE<br>3. P-SOURCE<br>4. P-GATE<br>5. P-DRAIN<br>6. P-DRAIN<br>7. N-DRAIN<br>8. N-DRAIN                                                     | <b>STYLE 15:</b><br>PIN 1. ANODE 1<br>2. ANODE 1<br>3. ANODE 1<br>4. ANODE 1<br>5. CATHODE, COMMON<br>6. CATHODE, COMMON<br>7. CATHODE, COMMON<br>8. CATHODE, COMMON               | <b>STYLE 16:</b><br>PIN 1. EMITTER, DIE #1<br>2. BASE, DIE #1<br>3. EMITTER, DIE #2<br>4. BASE, DIE #2<br>5. COLLECTOR, DIE #2<br>6. COLLECTOR, DIE #2<br>7. COLLECTOR, DIE #1<br>8. COLLECTOR, DIE #1 |
| <b>STYLE 17:</b><br>PIN 1. VCC<br>2. V2OUT<br>3. V1OUT<br>4. TXE<br>5. RXE<br>6. VEE<br>7. GND<br>8. ACC                                                                                          | <b>STYLE 18:</b><br>PIN 1. ANODE<br>2. ANODE<br>3. SOURCE<br>4. GATE<br>5. DRAIN<br>6. DRAIN<br>7. CATHODE<br>8. CATHODE                                                                 | <b>STYLE 19:</b><br>PIN 1. SOURCE 1<br>2. GATE 1<br>3. SOURCE 2<br>4. GATE 2<br>5. DRAIN 2<br>6. MIRROR 2<br>7. DRAIN 1<br>8. MIRROR 1                                             | <b>STYLE 20:</b><br>PIN 1. SOURCE (N)<br>2. GATE (N)<br>3. SOURCE (P)<br>4. GATE (P)<br>5. DRAIN<br>6. DRAIN<br>7. DRAIN<br>8. DRAIN                                                                   |
| <b>STYLE 21:</b><br>PIN 1. CATHODE 1<br>2. CATHODE 2<br>3. CATHODE 3<br>4. CATHODE 4<br>5. CATHODE 5<br>6. COMMON ANODE<br>7. COMMON ANODE<br>8. CATHODE 6                                        | <b>STYLE 22:</b><br>PIN 1. I/O LINE 1<br>2. COMMON CATHODE/VCC<br>3. COMMON CATHODE/VCC<br>4. I/O LINE 3<br>5. COMMON ANODE/GND<br>6. I/O LINE 4<br>7. I/O LINE 5<br>8. COMMON ANODE/GND | <b>STYLE 23:</b><br>PIN 1. LINE 1 IN<br>2. COMMON ANODE/GND<br>3. COMMON ANODE/GND<br>4. LINE 2 IN<br>5. LINE 2 OUT<br>6. COMMON ANODE/GND<br>7. COMMON ANODE/GND<br>8. LINE 1 OUT | <b>STYLE 24:</b><br>PIN 1. BASE<br>2. EMITTER<br>3. COLLECTOR/ANODE<br>4. COLLECTOR/ANODE<br>5. CATHODE<br>6. CATHODE<br>7. COLLECTOR/ANODE<br>8. COLLECTOR/ANODE                                      |
| <b>STYLE 25:</b><br>PIN 1. VIN<br>2. N/C<br>3. REXT<br>4. GND<br>5. IOUT<br>6. IOUT<br>7. IOUT<br>8. IOUT                                                                                         | <b>STYLE 26:</b><br>PIN 1. GND<br>2. dv/dt<br>3. ENABLE<br>4. ILIMIT<br>5. SOURCE<br>6. SOURCE<br>7. SOURCE<br>8. VCC                                                                    | <b>STYLE 27:</b><br>PIN 1. ILIMIT<br>2. OVLO<br>3. UVLO<br>4. INPUT+<br>5. SOURCE<br>6. SOURCE<br>7. SOURCE<br>8. DRAIN                                                            | <b>STYLE 28:</b><br>PIN 1. SW_TO_GND<br>2. DASIC_OFF<br>3. DASIC_SW_DET<br>4. GND<br>5. V_MON<br>6. VBULK<br>7. VBULK<br>8. VIN                                                                        |
| <b>STYLE 29:</b><br>PIN 1. BASE, DIE #1<br>2. EMITTER, #1<br>3. BASE, #2<br>4. EMITTER, #2<br>5. COLLECTOR, #2<br>6. COLLECTOR, #2<br>7. COLLECTOR, #1<br>8. COLLECTOR, #1                        | <b>STYLE 30:</b><br>PIN 1. DRAIN 1<br>2. DRAIN 1<br>3. GATE 2<br>4. SOURCE 2<br>5. SOURCE 1/DRAIN 2<br>6. SOURCE 1/DRAIN 2<br>7. SOURCE 1/DRAIN 2<br>8. GATE 1                           |                                                                                                                                                                                    |                                                                                                                                                                                                        |

|                         |                    |                                                                                                                                                                                     |
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| <b>DESCRIPTION:</b>     | <b>SOIC-8 NB</b>   | <b>PAGE 2 OF 2</b>                                                                                                                                                                  |

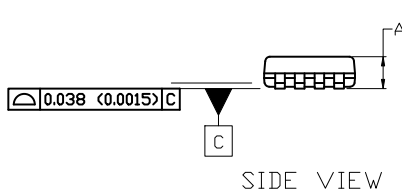
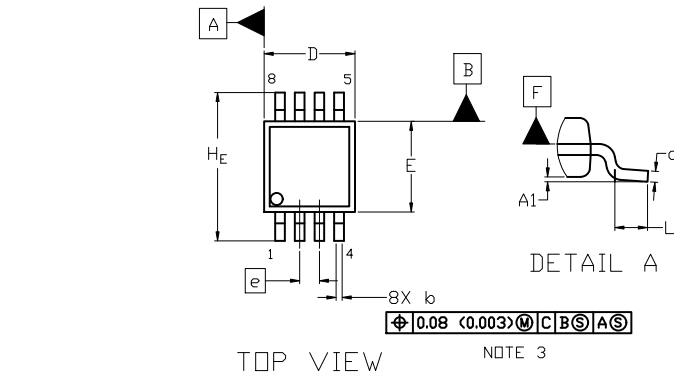
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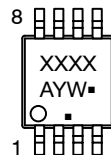
SCALE 2:1

Micro8  
CASE 846A-02  
ISSUE K

DATE 16 JUL 2020



GENERIC  
MARKING DIAGRAM\*



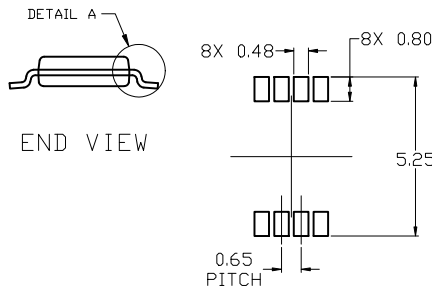
XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION  $b$  DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS  $D$  AND  $E$  DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION  $E$  DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS  $D$  AND  $E$  ARE DETERMINED AT DATUM  $F$ .
5. DATUMS  $A$  AND  $B$  ARE TO BE DETERMINED AT DATUM  $F$ .
6.  $A1$  IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM-10.

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN.        | NOM. | MAX. |
| A   | ---         | ---  | 1.10 |
| A1  | 0.05        | 0.08 | 0.15 |
| b   | 0.25        | 0.33 | 0.40 |
| c   | 0.13        | 0.18 | 0.23 |
| D   | 2.90        | 3.00 | 3.10 |
| E   | 2.90        | 3.00 | 3.10 |
| e   | 0.65 BSC    |      |      |
| HE  | 4.75        | 4.90 | 5.05 |
| L   | 0.40        | 0.55 | 0.70 |

STYLE 1:

- PIN 1. SOURCE
- SOURCE
- SOURCE
- GATE
- DRAIN
- DRAIN
- DRAIN
- DRAIN

STYLE 2:

- PIN 1. SOURCE 1
- GATE 1
- SOURCE 2
- GATE 2
- DRAIN 2
- DRAIN 2
- DRAIN 1
- DRAIN 1

STYLE 3:

- PIN 1. N-SOURCE
- N-GATE
- P-SOURCE
- P-GATE
- P-DRAIN
- P-DRAIN
- N-DRAIN
- N-DRAIN

|                  |             |                                                                                                                                                                                  |
|------------------|-------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| DESCRIPTION:     | MICRO8      | PAGE 1 OF 1                                                                                                                                                                      |

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